NOTES: UNLESS OTHERWISE SPECIFIED

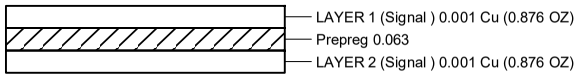
1. MAT'L: Copper clad plated sheet per MIL-P-13949/4, Type GFM,

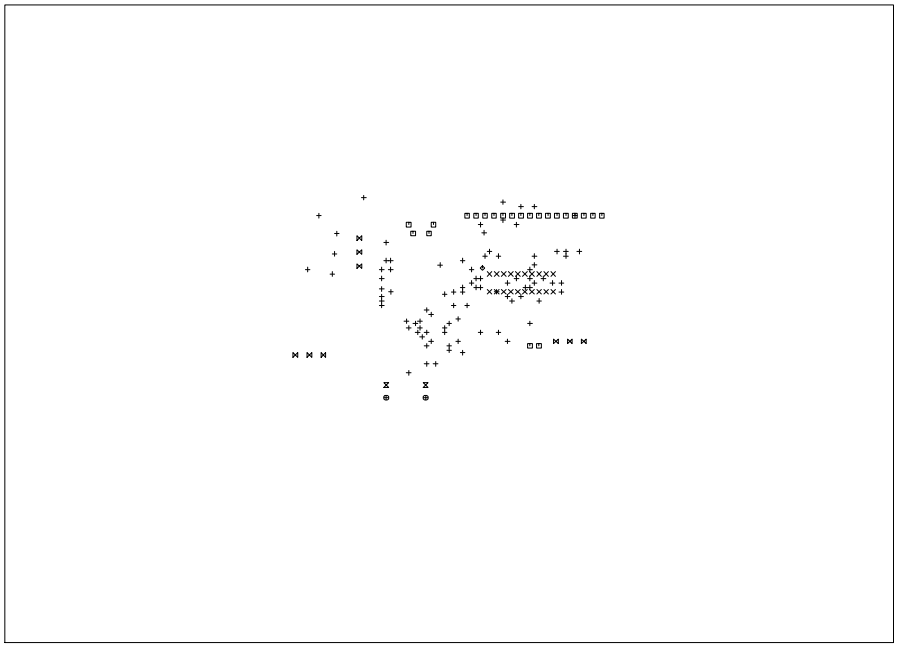
   A. Copper Weight:
      a) Outer Layers 1.5 OZ.
      b) Inner Plane Layers 1 OZ.
      c) Inner Signal Layers 1 OZ.

   B. Laminate using Pre-Preg Material Per MIL-P-13949/12, Type PC-GF. Tg minimum 170 deg C.

2. Overall Board thickness to be .093 +/- .009.
3. Unless otherwise specified all hole dimensions apply after platting. All plated through holes to have a minimum of .001 copper.
4. All holes shall be located within .003 diameter of true position. Layer to layer registration shall be within .005. All holes surrounded by land shall have a minimum annular ring of .001. Tangency on holes with breakout is acceptable.
5. Conductor widths and spacing shall be within +/- 20% of artwork originals.
6. Apply solder mask (liquid photo imageable) over bare copper, solder mask to be per IPC-SM-84D, Type B, Class 3, Color: Transparent Green. All exposed conductive surfaces to be solder coated.
7. Ware or twist of board shall not exceed .0075 inch per inch.

LAYER STACK-UP





DRILL PATTERN

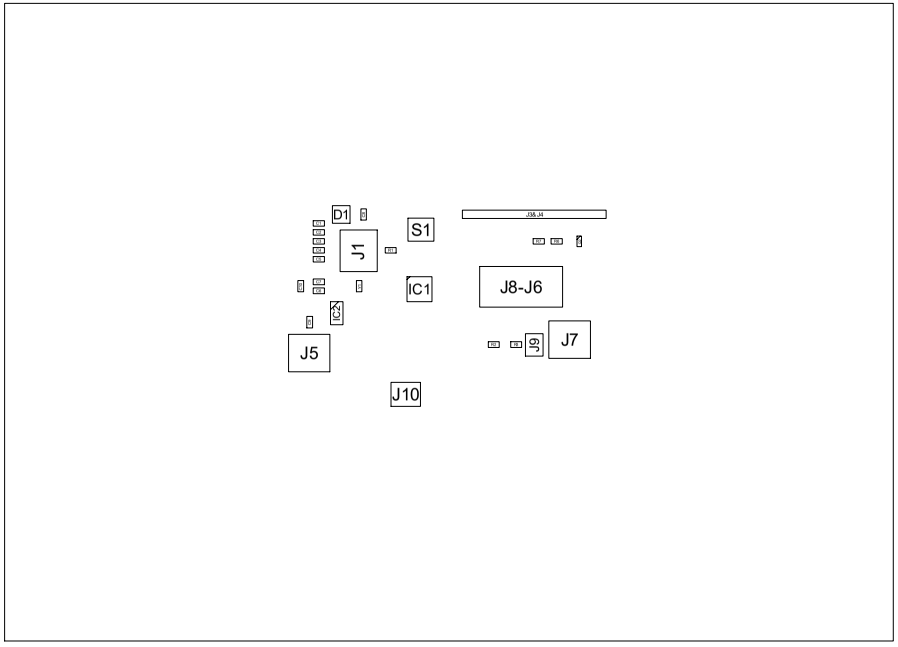
Drill Chart

Qty	Size	Sym	Plated	Tolerance
91	0.013	+	Yes	+0/-0.013
20	0.033	X	Yes	+/-0.003
22	0.041	square	Yes	+/-0.003
1	0.047	diamond	No	+/-0.002
2	0.060	hourglass	Yes	+/-0.003
9	0.069	bowtie	Yes	+/-0.003
2	0.075	circle+	Yes	+/-0.003

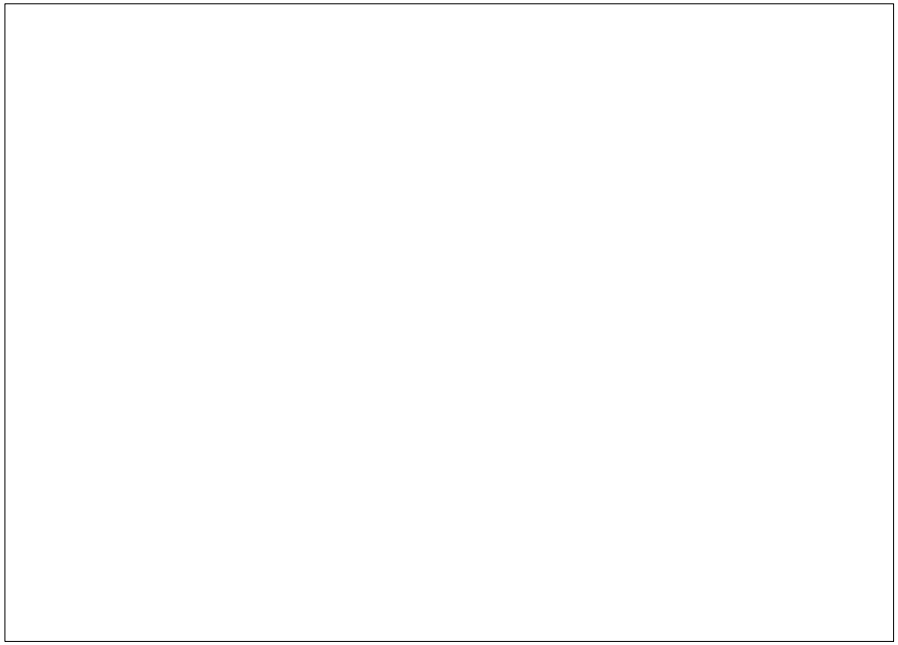
DRAWN	DATE	TITLE				
ENGINEER	DATE					
CHECKED	DATE					
APPROVED	DATE	SIZE	CAGE CODE	DWG NO		REV
ISSUED	DATE	Cust				A
		SCALE 1 : 1			SHEET 1 OF 1	

NOTES: UNLESS OTHERWISE SPECIFIED

1. This is a static sensitive assembly- use static eliminating measures during assembly and handling.
2. Manufacture to IPC 610A workmanship standards.
3. Trim component leads within .062 from solder side of PWA with exception of indicated area, which must be trimmed to .010 +/- .010
4. Apply part number and serial number labels in areas shown.
5. Install item 19 (120-1032-001 heat sink as follows:
   A. Clean bottom surface of heat sink and mounting
   B. Apply sufficient amount of Item 21 (120-1031-001), epoxy tube, to bottom of heat sink.
   C. Apply Item 21, activator tube to mounting surface of Pentium Module
   D. Mount heat sink onto Pentium Module and allow to sit for 30 seconds.
6. Discard nylon washer supplied with Item 16 (120-9958-002)



Top-side View



Bottom-side View

Parts List				
Item No	Qty	Ref Des	Part Name	Description
	1	J8-J6	559172010	
	1	S1	95C06A3RAT	
	1	Y1	ABS07	
	10	C1-C10	CAPC3216X95N	
	1	J3&J4	HDRV16W87P0X254	
1	1	PCB	PCB	
	1	IC1	QFP80P900X900X16	
	5	R1-R3, R6-R7	RESC3116X65N	
	1	J9	SHDR2W87P0X254_	
	3	J1, J5, J7	SHDR3W155P0X396	
	1	IC2	SOT229P700X180-4	
	1	Q2	SOT96P237X111-3N	
	1	J10	UJCHPLG5MSMTTR	
	1	D1	WS2812	

DRAWN	DATE	TITLE			
ENGINEER	DATE				
CHECKED	DATE				
APPROVED	DATE	SIZE Cust	CAGE CODE	DWG NO	REV A
ISSUED	DATE	SCALE 1 : 1			SHEET 1 OF 1